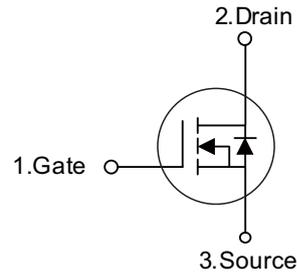


■ PRODUCT CHARACTERISTICS

VDSS	650V
$R_{DS(on)max}(@V_{GS} = 10\text{ V})$	0.18Ω
Qg@type	30nC
ID	20A

Symbol



■ APPLICATIONS

- * Power factor correction
- * Switched mode power supplies
- * Uninterruptible power supply

■ FEATURES

- * low $R_{DS(on)}$
- * low gate charge
- * RoHS compliant



■ ORDER INFORMATION

Order codes		Package	Packing
Halogen-Free	Halogen		
N/A	SPF65R180	TO-220F	50 pieces/Tube
N/A	SPT68R180	TO-220	50 pieces/Tube

■ ABSOLUTE MAXIMUM RATINGS ($T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	650	V
Continuous drain current ($T_C = 25^\circ\text{C}$)	I_D	20	A
Pulsed drain current	I_{DM}	60	A
Gate-Source voltage	V_{GSS}	± 30	V
Avalanche energy, single pulse	E_{AS}	600	mJ
Avalanche current, repetitive	I_{AR}	20	A
Power Dissipation ($T_C = 25^\circ\text{C}$)	TO-220	90	W
	TO-220F	31.8	W
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$
Continuous diode forward current	I_S	20	A
Diode pulse current	$I_{S,pulse}$	60	A

■ THERMAL CHARACTERISTICS

Parameter	Symbol	Value	Unit	
Thermal Resistance, Junction-to-Case	TO-220F	$R_{\theta JC}$	4.2	$^\circ\text{C/W}$
	TO-220	$R_{\theta JC}$	0.86	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient	TO-220F	$R_{\theta JA}$	88	$^\circ\text{C/W}$
	TO-220	$R_{\theta JA}$	118	$^\circ\text{C/W}$

■ ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static characteristics						
Drain-source breakdown voltage	BV_{DSS}	$V_{GS}=0\text{ V}, I_D=0.25\text{ mA}$	650	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=0.25\text{ mA}$	2.5	3.5	4.5	V
Drain cut-off current	I_{DSS}	$V_{DS}=650\text{ V}, V_{GS}=0\text{ V},$ $T_J = 125^\circ\text{C}$	-	-	1	μA
			-	10	-	μA
Gate leakage current, Forward	I_{GSSF}	$V_{GS}=30\text{ V}, V_{DS}=0\text{ V}$	-	-	100	nA
Gate leakage current, Reverse	I_{GSSR}	$V_{GS}=-30\text{ V}, V_{DS}=0\text{ V}$	-	-	-100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=10\text{ V}, I_D=10\text{ A}$ $T_J = 150^\circ\text{C}$	-	0.15	0.18	Ω
			-	0.4	-	Ω
Gate resistance	R_G	$f=1\text{ MHz}$, open drain	-	4.5	-	Ω
Dynamic characteristics						
Input capacitance	C_{iss}	$V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V},$ $f = 1\text{ MHz}$	-	2637	-	pF
Output capacitance	C_{oss}		-	1250	-	pF
Reverse transfer capacitance	C_{rss}		-	17	-	pF
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 300\text{ V}, I_D = 10\text{ A}$ $R_G = 10\Omega, V_{GS}=15\text{ V}$	-	23.4	-	ns
Rise time	t_r		-	33	-	ns
Turn-off delay time	$t_{d(off)}$		-	121	-	ns
Fall time	t_f		-	7.5	-	ns
Gate charge characteristics						
Gate to source charge	Q_{gs}	$V_{DD}=520\text{ V}, I_D=10\text{ A},$ $V_{GS}=0\text{ to }10\text{ V}$	-	8	-	nC
Gate to drain charge	Q_{gd}		-	10	-	nC
Gate charge total	Q_g		-	30	-	nC
Gate plateau voltage	$V_{plateau}$		-	5	-	V
Reverse diode characteristics						
Diode forward voltage	V_{SD}	$V_{GS}=0\text{ V}, I_F=10\text{ A}$	-	-	1.2	V
Reverse recovery time	t_{rr}	$V_R=50\text{ V}, I_F=10\text{ A},$ $di_F/dt=100\text{ A}/\mu\text{s}$	-	285	-	ns
Reverse recovery charge	Q_{rr}		-	4.1	-	μC
Peak reverse recovery current	I_{rrm}		-	28.4	-	A

■ ELECTRICAL CHARACTERISTICS DIAGRAMS

Figure 1. On-Region Characteristics

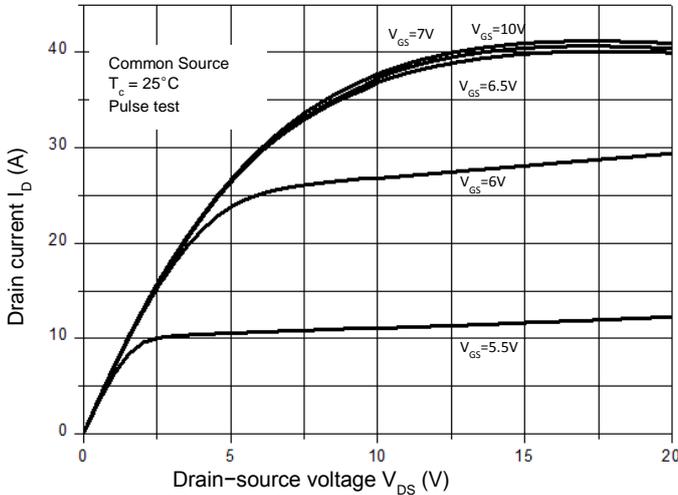


Figure 2. Transfer Characteristics

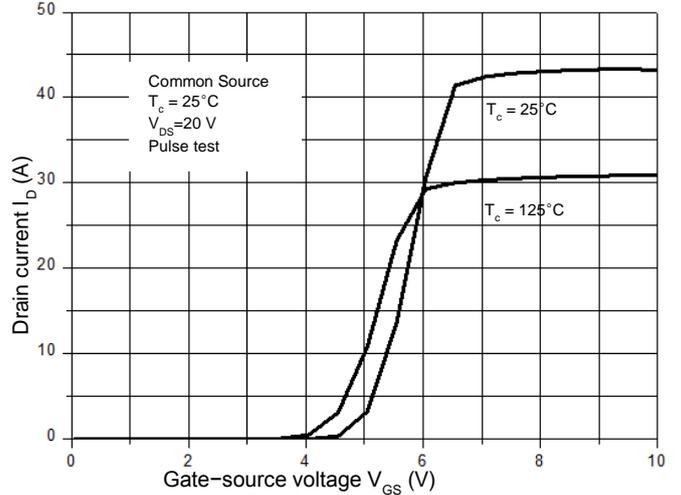


Figure 3. On-Resistance Variation vs. Drain Current

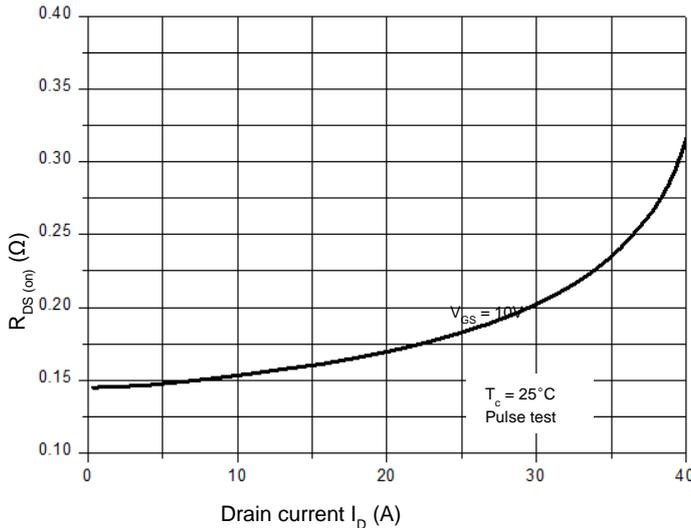


Figure 4. Threshold Voltage vs. Temperature

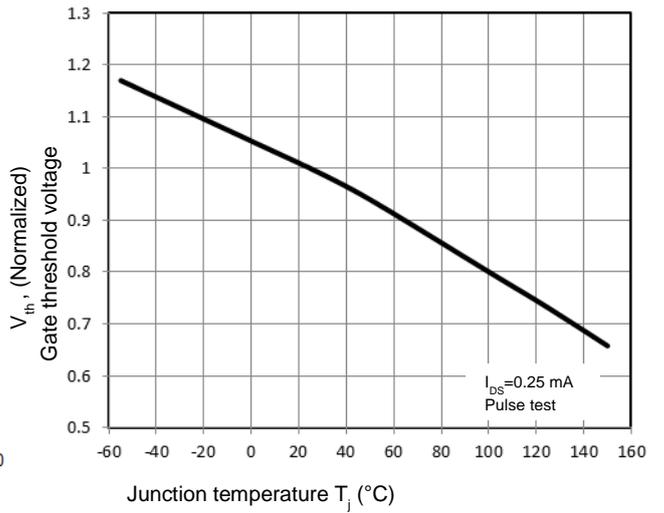


Figure 5. Breakdown Voltage vs. Temperature

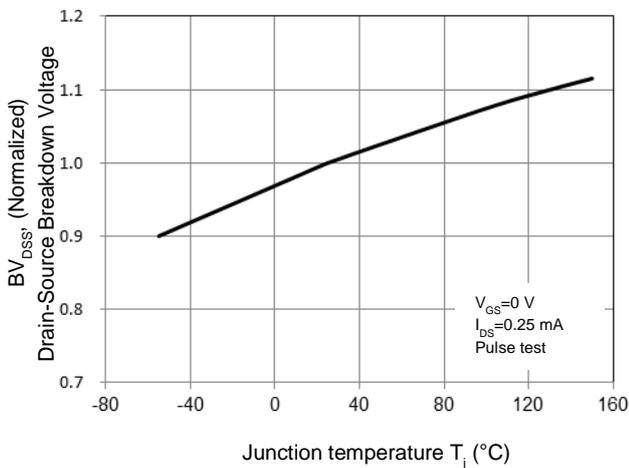
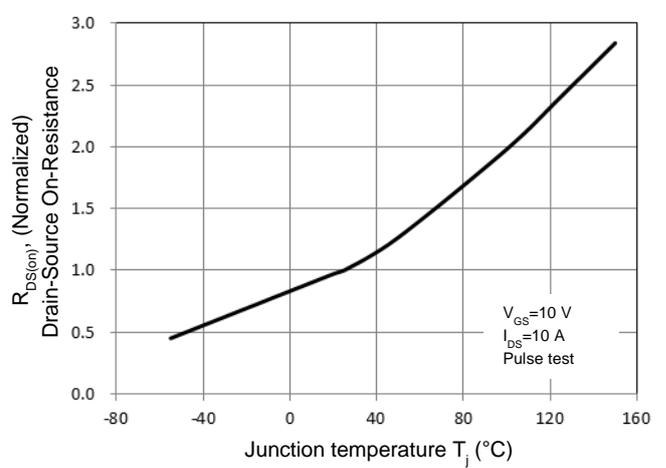


Figure 6. On-Resistance vs. Temperature



ELECTRICAL CHARACTERISTICS DIAGRAMS(Cont.)

Figure 7. Capacitance Characteristics

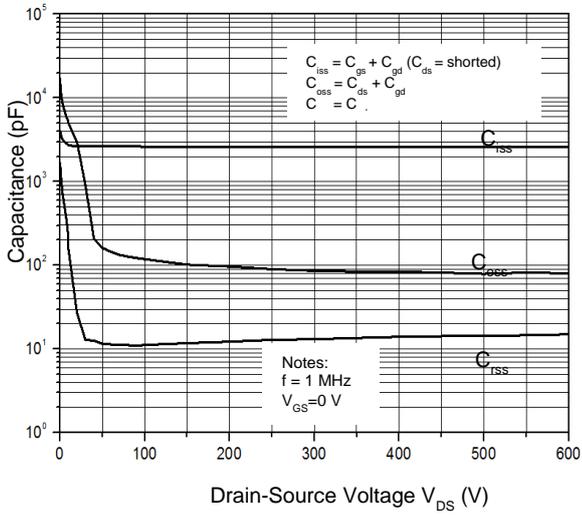


Figure 8. Gate Charge Characterist

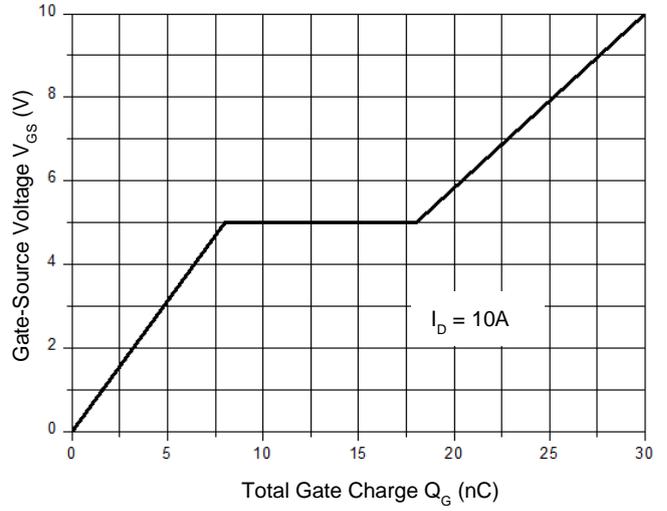


Figure 9 Maximum Safe Operating Area

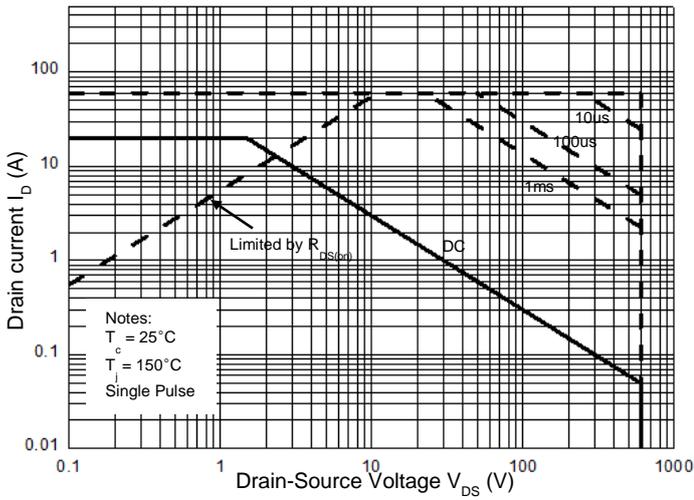
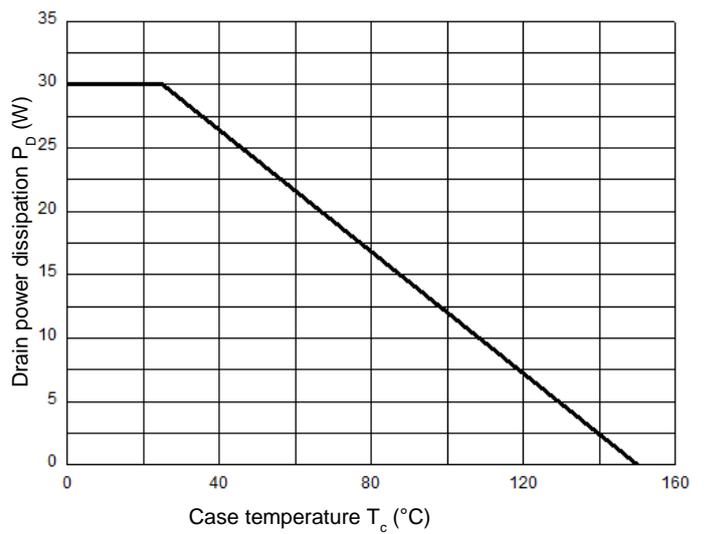


Figure 10 Power Dissipation vs. Temperature



■ TO-220-3L PACKAGE OUTLINE DIMENSIONS

